

HCTS138MS

Radiation Hardened Inverting 3-to-8 Line Decoder/Demultiplexer

FN2462

Rev 3.00

September 12, 2005

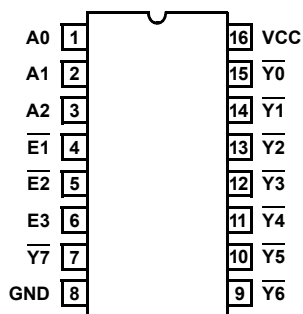
The Intersil HCTS138MS is a Radiation Hardened 3-to-8 line Decoder/Demultiplexer. The outputs are active in the low state. Two active low and one active high enables ($\overline{E1}$, $\overline{E2}$, E3) are provided. If the device is enabled, the binary inputs (A0, A1, A2) determine which one of the eight normally high outputs will go to a low logic level.

The HCTS138MS utilizes advanced CMOS/SOS technology to achieve high-speed operation. This device is a member of radiation hardened, high-speed, CMOS/SOS Logic Family.

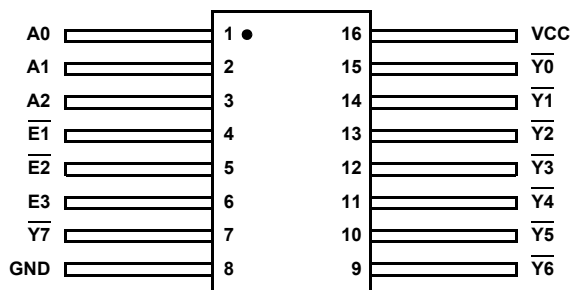
The HCTS138MS is supplied in a 16 lead Ceramic flatpack (K suffix) or a SBDIP Package (D suffix).

Pinouts

**16 LEAD CERAMIC DUAL-IN-LINE METAL SEAL PACKAGE (SBDIP)
MIL-STD-1835 CDIP2-T16
TOP VIEW**



**16 LEAD CERAMIC METAL SEAL FLATPACK PACKAGE (FLATPACK)
MIL-STD-1835 CDFP4-F16
TOP VIEW**



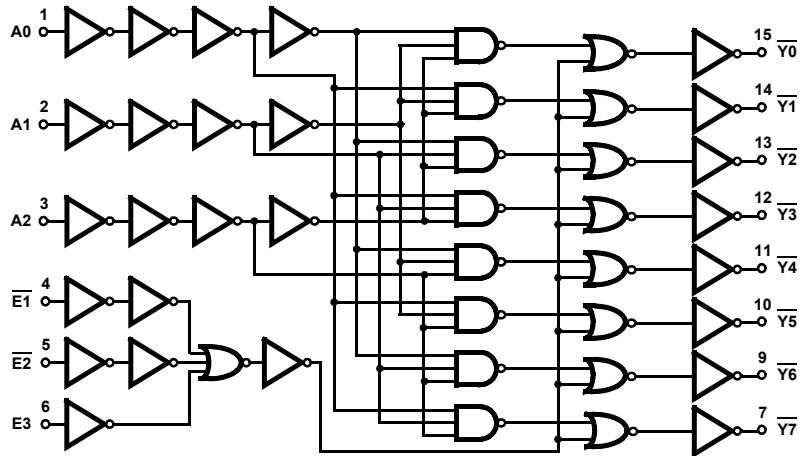
Features

- 3 Micron Radiation Hardened SOS CMOS
- Total Dose 200K RAD (Si)
- SEP Effective LET No Upsets: >100 MEV-cm²/mg
- Single Event Upset (SEU) Immunity < 2 x 10⁻⁹ Errors/Bit-Day (Typ)
- Latch-Up Free Under Any Conditions
- Fanout (Over Temperature Range)
 - Bus Driver Outputs - 15 LSTTL Loads
- Military Temperature Range: -55°C to +125°C
- Significant Power Reduction Compared to LSTTL ICs
- DC Operating Voltage Range: 4.5V to 5.5V
- LSTTL Input Compatibility
 - VIL = 0.8V Max
 - VIH = VCC/2 Min
- Input Current Levels $I_i \leq 5\mu A$ at VOL, VOH

Ordering Information

PART NUMBER	TEMP RANGE	SCREENING LEVEL	PACKAGE
HCTS138DMSR	-55°C to +125°C	Intersil Class S Equivalent	16 Lead SBDIP
HCTS138KMSR	-55°C to +125°C	Intersil Class S Equivalent	16 Lead Ceramic Flatpack
HCTS138HMSR	+25°C	Die	Die

Functional Diagram



TRUTH TABLE

INPUTS						OUTPUTS							
ENABLE			A2	A1	A0	$\overline{Y0}$	$\overline{Y1}$	$\overline{Y2}$	$\overline{Y3}$	$\overline{Y4}$	$\overline{Y5}$	$\overline{Y6}$	$\overline{Y7}$
E3	$\overline{E2}$	$\overline{E1}$											
X	X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	X	H	H	H	H	H	H	H	H
X	H	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	H	L	L	H	H	H	H	L	H	H	H
H	L	L	H	L	H	H	H	H	H	H	L	H	H
H	L	L	H	H	L	H	H	H	H	H	H	L	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L

H = High Level, L = Low Level, X = Don't Care

Absolute Maximum Ratings

Supply Voltage (VCC)	-0.5V to +7.0V
Input Voltage Range, All Inputs	-0.5V to VCC +0.5V
DC Input Current, Any One Input	±10mA
DC Drain Current, Any One Output (All Voltage Reference to the VSS Terminal)	±25mA
Storage Temperature Range (TSTG)	-65°C to +150°C
Lead Temperature (Soldering 10sec)	+265°C
Junction Temperature (TJ)	+175°C
ESD Classification	Class 1

Reliability Information

Thermal Resistance	θ_{JA}	θ_{JC}
SBDIP Package	73°C/W	24°C/W
Ceramic Flatpack Package	114°C/W	29°C/W
Maximum Package Power Dissipation at +125°C Ambient		
SBDIP Package	0.68W	
Ceramic Flatpack Package	0.44W	
If device power exceeds package dissipation capability, provide heat sinking or derate linearly at the following rate:		
SBDIP Package	13.7mW/°C	
Ceramic Flatpack Package	8.8mW/°C	

CAUTION: As with all semiconductors, stress listed under "Absolute Maximum Ratings" may be applied to devices (one at a time) without resulting in permanent damage. This is a stress rating only. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. The conditions listed under "Electrical Performance Characteristics" are the only conditions recommended for satisfactory device operation.

Operating Conditions

Supply Voltage	+4.5V to +5.5V	Input Low Voltage (VIL)	0.0V to 0.8V
Input Rise and Fall Times at VCC = 4.5V (TR, TF)	500ns Max	Input High Voltage (VIH)	VCC/2 to VCC
Operating Temperature Range (TA)	-55°C to +125°C		

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Quiescent Current	ICC	VCC = 5.5V, VIN = VCC or GND	1	+25°C	-	40	μA
			2, 3	+125°C, -55°C	-	750	μA
Output Current (Sink)	IOL	VCC = 4.5V, VIH = 4.5V, VOU = 0.4V, VIL = 0V	1	+25°C	7.2	-	mA
			2, 3	+125°C, -55°C	6.0	-	mA
Output Current (Source)	IOH	VCC = 4.5V, VIH = 4.5V, VOU = VCC -0.4V, VIL = 0V	1	+25°C	-7.2	-	mA
			2, 3	+125°C, -55°C	-6.0	-	mA
Output Voltage Low	VOL	VCC = 4.5V, VIH = 2.25V, IOL = 50μA, VIL = 0.8V	1, 2, 3	+25°C, +125°C, -55°C	-	0.1	V
		VCC = 5.5V, VIH = 2.75V, IOL = 50μA, VIL = 0.8V	1, 2, 3	+25°C, +125°C, -55°C	-	0.1	V
Output Voltage High	VOH	VCC = 4.5V, VIH = 2.25V, IOH = -50μA, VIL = 0.8V	1, 2, 3	+25°C, +125°C, -55°C	VCC -0.1	-	V
		VCC = 5.5V, VIH = 2.75V, IOH = -50μA, VIL = 0.8V	1, 2, 3	+25°C, +125°C, -55°C	VCC -0.1	-	V
Input Leakage Current	IIN	VCC = 5.5V, VIN = VCC or GND	1	+25°C	-	±0.5	μA
			2, 3	+125°C, -55°C	-	±5.0	μA
Noise Immunity Functional Test	FN	VCC = 4.5V, VIH = 2.25V, VIL = 0.8V, (Note 2)	7, 8A, 8B	+25°C, +125°C, -55°C	-	-	-

NOTES:

- All voltages reference to device GND.
- For functional tests $VO \geq 4.0V$ is recognized as a logic "1", and $VO \leq 0.5V$ is recognized as a logic "0".

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTES 1, 2) CONDITIONS	GROUP A SUBGRO UPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Address to Output	TPLH	VCC = 4.5V	9	+25°C	2	25	ns
			10, 11	+125°C, -55°C	2	30	ns
	TPHL	VCC = 4.5V	9	+25°C	2	28	ns
			10, 11	+125°C, -55°C	2	39	ns
Enable to Output	TPLH	VCC = 4.5V	9	+25°C	2	26	ns
			10, 11	+125°C, -55°C	2	31	ns
	TPHL	VCC = 4.5V	9	+25°C	2	26	ns
			10, 11	+125°C, -55°C	2	34	ns

NOTES:

1. All voltages referenced to device GND.
2. AC measurements assume $R_L = 500\Omega$, $C_L = 50\text{pF}$, Input $T_R = T_F = 3\text{ns}$, $V_{IL} = \text{GND}$, $V_{IH} = 3\text{V}$.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Capacitance Power Dissipation	CPD	VCC = 5.0V, f = 1MHz	1	+25°C	-	89	pF
			1	+125°C, -55°C	-	102	pF
Input Capacitance	CIN	VCC = 5.0V, f = 1MHz	1	+25°C	-	10	pF
			1	+125°C, -55°C	-	10	pF
Output Transition Time	TTHL TTLH	VCC = 4.5V	1	+25°C	-	15	ns
			1	+125°C, -55°C	-	22	ns

NOTE:

1. The parameters listed in Table 3 are controlled via design or process parameters. Min and Max Limits are guaranteed but not directly tested. These parameters are characterized upon initial design release and upon design changes which affect these characteristics.

TABLE 4. DC POST RADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTES 1, 2) CONDITIONS	TEMPERATURE	200K RAD LIMITS		UNITS
				MIN	MAX	
Quiescent Current	ICC	VCC = 5.5V, VIN = VCC or GND	+25°C	-	0.75	mA
Output Current (Sink)	IOL	VCC = 4.5V, VIN = VCC or GND, VOUT = 0.4V	+25°C	6.0	-	mA
Output Current (Source)	IOH	VCC = 4.5V, VIN = VCC or GND, VOUT = VCC - 0.4V	+25°C	-6.0	-	mA

TABLE 4. DC POST RADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

PARAMETER	SYMBOL	(NOTES 1, 2) CONDITIONS	TEMPERATURE	200K RAD LIMITS		UNITS
				MIN	MAX	
Output Voltage Low	VOL	VCC = 4.5V and 5.5V, VIH = VCC/2, VIL = 0.8V at 200K RAD, IOL = 50 μ A	+25 $^{\circ}$ C	-	0.1	V
Output Voltage High	VOH	VCC = 4.5V and 5.5V, VIH = VCC/2, VIL = 0.8V at 200K RAD, IOH = -50 μ A	+25 $^{\circ}$ C	VCC -0.1	-	V
Input Leakage Current	IIN	VCC = 5.5V, VIN = VCC or GND	+25 $^{\circ}$ C	-	\pm 5	μ A
Noise Immunity Functional Test	FN	VCC = 4.5V, VIH = 2.25V, VIL = 0.8V, (Note 3)	+25 $^{\circ}$ C	-	-	-
Address to Output	TPLH	VCC = 4.5V	+25 $^{\circ}$ C	2	30	ns
	TPHL	VCC = 4.5V	+25 $^{\circ}$ C	2	39	ns
Enable to Output	TPLH	VCC = 4.5V	+25 $^{\circ}$ C	2	31	ns
	TPHL	VCC = 4.5V	+25 $^{\circ}$ C	2	34	ns

NOTES:

- All voltages referenced to device GND.
- AC measurements assume RL = 500 Ω , CL = 50pF, Input TR = TF = 3ns, VIL = GND, VIH = 3V.
- For functional tests VO \geq 4.0V is recognized as a logic "1", and VO \leq 0.5V is recognized as a logic "0".

TABLE 5. BURN-IN AND OPERATING LIFE TEST, DELTA PARAMETERS (+25 $^{\circ}$ C)

PARAMETER	GROUP B SUBGROUP	DELTA LIMIT
ICC	5	12 μ A
IOL/IOH	5	-15% of 0 Hour

TABLE 6. APPLICABLE SUBGROUPS

CONFORMANCE GROUPS	METHOD	GROUP A SUBGROUPS	READ AND RECORD
Initial Test (Preburn-In)	100%/5004	1, 7, 9	ICC, IOL/H
Interim Test I (Postburn-In)	100%/5004	1, 7, 9	ICC, IOL/H
Interim Test II (Postburn-In)	100%/5004	1, 7, 9	ICC, IOL/H
PDA	100%/5004	1, 7, 9, Deltas	
Interim Test III (Postburn-In)	100%/5004	1, 7, 9	ICC, IOL/H
PDA	100%/5004	1, 7, 9, Deltas	
Final Test	100%/5004	2, 3, 8A, 8B, 10, 11	
Group A (Note 1)	Sample/5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11	
Group B	Subgroup B-5	Sample/5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11, Deltas
	Subgroup B-6	Sample/5005	1, 7, 9
Group D	Sample/5005	1, 7, 9	

NOTE:

- Alternate group A inspection in accordance with method 5005 of MIL-STD-883 may be exercised.

TABLE 7. TOTAL DOSE IRRADIATION

CONFORMANCE GROUPS	METHOD	TEST		READ AND RECORD	
		PRE RAD	POST RAD	PRE RAD	POST RAD
Group E Subgroup 2	5005	1, 7, 9	Table 4	1, 9	Table 4 (Note 1)

NOTE:

1. Except FN test which will be performed 100% Go/No-Go.

TABLE 8. STATIC AND DYNAMIC BURN-IN TEST CONNECTIONS

OPEN	GROUND	1/2 VCC = 3V ± 0.5V	VCC = 6V ± 0.5V	OSCILLATOR	
				50kHz	25kHz
STATIC BURN-IN I TEST CONNECTIONS (Note 1)					
7, 9 - 15	1 - 6, 8		16		
STATIC BURN-IN II TEST CONNECTIONS (Note 1)					
7, 9 - 15	8	-	1 - 6, 16	-	-
DYNAMIC BURN-IN TEST CONNECTIONS (Note 2)					
-	4, 5, 8	7, 9 - 15	3, 6, 16	2	1

NOTES:

1. Each pin except VCC and GND will have a resistor of 10KΩ ± 5% for static burn-in
2. Each pin except VCC and GND will have a resistor of 680Ω ± 5% for dynamic burn-in

TABLE 9. IRRADIATION TEST CONNECTIONS

OPEN	GROUND	VCC = 5V ± 0.5V
7, 9 - 15	8	1 - 6, 16

NOTE: Each pin except VCC and GND will have a resistor of 47KΩ ± 5% for irradiation testing.
Group E, Subgroup 2, sample size is 4 dice/wafer 0 failures.

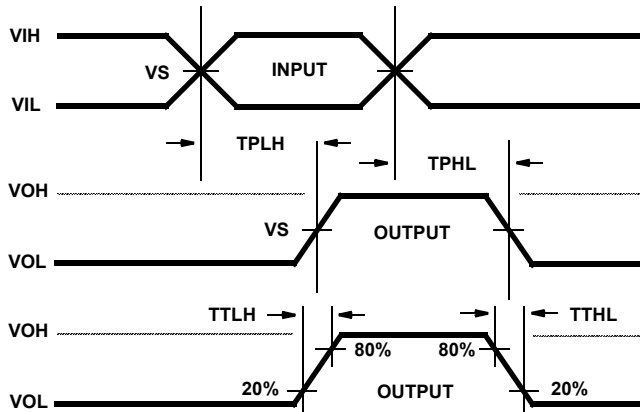
Intersil Space Level Product Flow - 'MS'

Wafer Lot Acceptance (All Lots) Method 5007 (Includes SEM)	100% Interim Electrical Test 1 (T1)
GAMMA Radiation Verification (Each Wafer) Method 1019, 4 Samples/Wafer, 0 Rejects	100% Delta Calculation (T0-T1)
100% Nondestructive Bond Pull, Method 2023	100% Static Burn-In 2, Condition A or B, 24 hrs. min., +125°C min., Method 1015
Sample - Wire Bond Pull Monitor, Method 2011	100% Interim Electrical Test 2 (T2)
Sample - Die Shear Monitor, Method 2019 or 2027	100% Delta Calculation (T0-T2)
100% Internal Visual Inspection, Method 2010, Condition A	100% PDA 1, Method 5004 (Notes 1 and 2)
100% Temperature Cycle, Method 1010, Condition C, 10 Cycles	100% Dynamic Burn-In, Condition D, 240 hrs., +125°C or Equivalent, Method 1015
100% Constant Acceleration, Method 2001, Condition per Method 5004	100% Interim Electrical Test 3 (T3)
100% PIND, Method 2020, Condition A	100% Delta Calculation (T0-T3)
100% External Visual	100% PDA 2, Method 5004 (Note 2)
100% Serialization	100% Final Electrical Test
100% Initial Electrical Test (T0)	100% Fine/Gross Leak, Method 1014
100% Static Burn-In 1, Condition A or B, 24 hrs. min., +125°C min., Method 1015	100% Radiographic, Method 2012 (Note 3)
	100% External Visual, Method 2009
	Sample - Group A, Method 5005 (Note 4)
	100% Data Package Generation (Note 5)

NOTES:

1. Failures from Interim electrical test 1 and 2 are combined for determining PDA 1.
2. Failures from subgroup 1, 7, 9 and deltas are used for calculating PDA. The maximum allowable PDA = 5% with no more than 3% of the failures from subgroup 7.
3. Radiographic (X-Ray) inspection may be performed at any point after serialization as allowed by Method 5004.
4. Alternate Group A testing may be performed as allowed by MIL-STD-883, Method 5005.
5. Data Package Contents:
 - Cover Sheet (Intersil Name and/or Logo, P.O. Number, Customer Part Number, Lot Date Code, Intersil Part Number, Lot Number, Quantity).
 - Wafer Lot Acceptance Report (Method 5007). Includes reproductions of SEM photos with percent of step coverage.
 - GAMMA Radiation Report. Contains Cover page, disposition, Rad Dose, Lot Number, Test Package used, Specification Numbers, Test equipment, etc. Radiation Read and Record data on file at Intersil.
 - X-Ray report and film. Includes penetrometer measurements.
 - Screening, Electrical, and Group A attributes (Screening attributes begin after package seal).
 - Lot Serial Number Sheet (Good units serial number and lot number).
 - Variables Data (All Delta operations). Data is identified by serial number. Data header includes lot number and date of test.
 - The Certificate of Conformance is a part of the shipping invoice and is not part of the Data Book. The Certificate of Conformance is signed by an authorized Quality Representative.

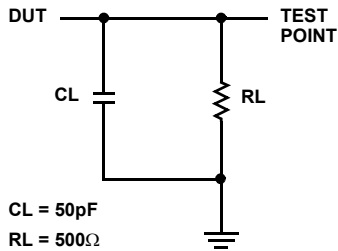
AC Timing Diagrams



AC VOLTAGE LEVELS

PARAMETER	HCTS	UNITS
VCC	4.50	V
VIH	3.00	V
VS	1.30	V
VIL	0	V
GND	0	V

AC Load Circuit



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Die Characteristics

DIE DIMENSIONS:
85 x 101 mils

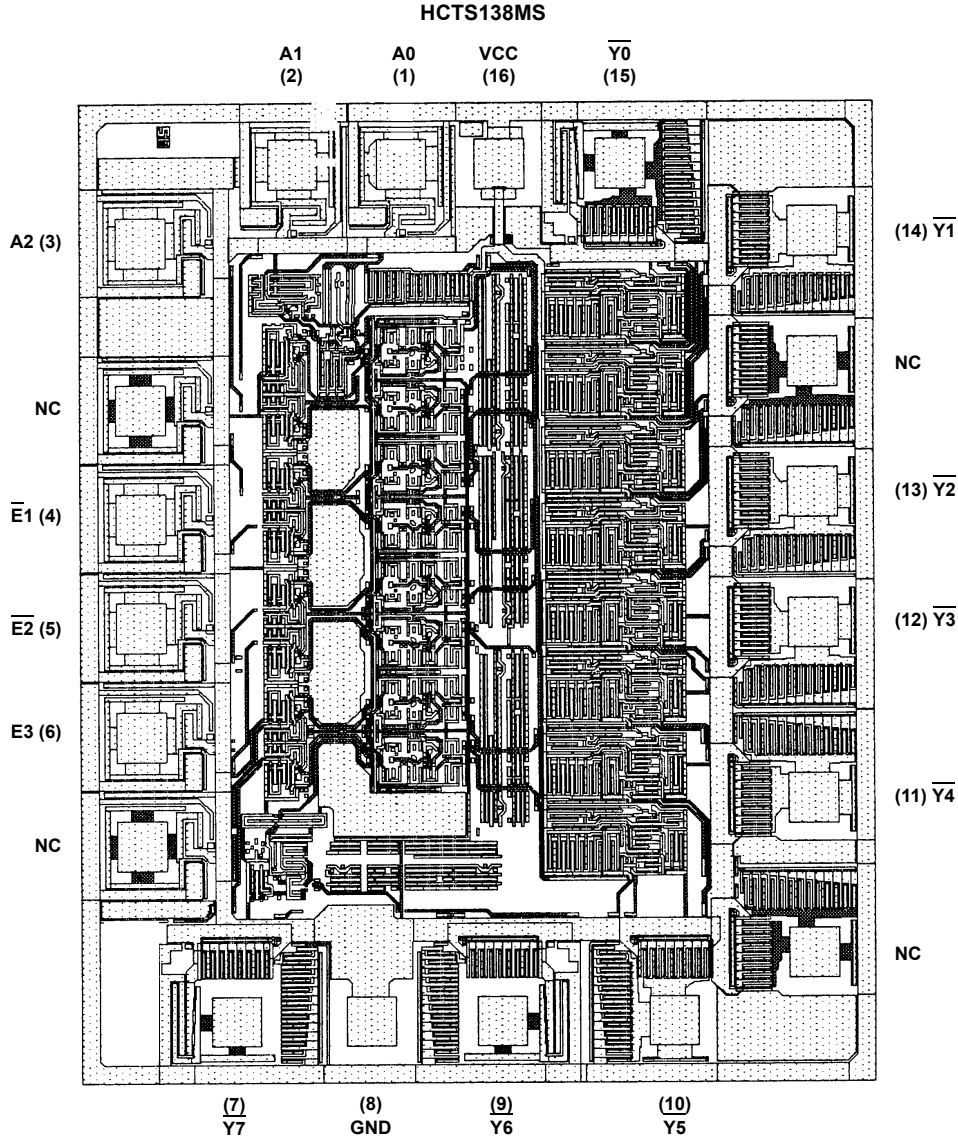
METALLIZATION:
Type: SiAl
Metal Thickness: $11\text{k}\text{\AA} \pm 1\text{k}\text{\AA}$

GLASSIVATION:
Type: SiO_2
Thickness: $13\text{k}\text{\AA} \pm 2.6\text{k}\text{\AA}$

WORST CASE CURRENT DENSITY:
 $<2.0 \times 10^5 \text{A/cm}^2$

BOND PAD SIZE:
 $100\mu\text{m} \times 100\mu\text{m}$
4 x 4 mils

Metallization Mask Layout



NOTE: The die diagram is a generic plot from a similar HCS device. It is intended to indicate approximate die size and bond pad location. The mask series for the HCTS138 is TA14461A.